

 深圳市鸿源精密器材有限公司	Product Specification	DOC. No.:EB1-AS1C-223		Rev.: B	Page: 1/4
	PART No.:	Approved/Date		Checked/Date	Made/Date
	RF3-1717-085CE-CT	ZO 2016.03.04		W.P.Lu 2016.03.04	Y.Y.Chen 2016.03.04

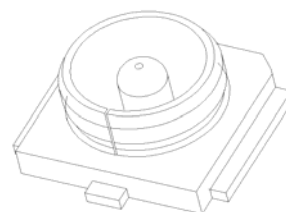
1、Scope(简述)

The product described in this paper is a SMT Type Micro Coaxial RF Receptacle ,whose part name in our comply is USS RF REC..It is special for Microstrip-to-Coaxial adapter in RF circuit,Such as Mobile Phone ,Wireless Net, MiniPCI,BlueTooth,PDA,GPS,Electric Measurement Instruments and so on.

本产品为超小表面贴装（USS RF 第 III 代），适用于 RF 电路微带同轴传输转接口,应用于移动电话,无线网络, 袖珍型 PCI, 蓝牙,掌上电脑, 全球定位系统, 电子测量仪器, 等等

2、Technical Parameters(技术参数)

2.1 Rated Voltage(额定电压)	60VAC (R. M. S)
2.2 Frequency Range(频率范围)	0~6GHz
2.3 Character Impedance(特性阻抗)	50Ω
2.4 Operate Temperature(工作温度)	-40℃ ~+90℃
2.5 Operate Humidity(工作湿度)	90% MAX



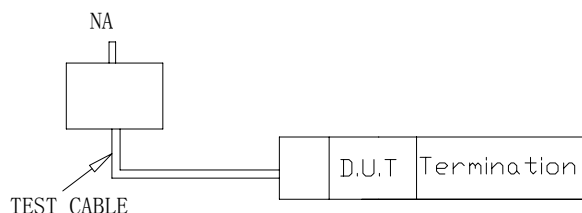
3、Electric Performance (电性能)

3.1 Dielectric Resistance(绝缘阻抗)	500MΩ
3.2 Dielectric Withstand Voltage(耐电压)	200V AC 1Min
3.3 Contact Resistance(接触阻抗)	
3.3.1 Inner Contact(内导体)	Initial(初始): 15 mΩ max After(测试后): 20 mΩ max
3.3.2 Outer Contact(外导体)	Initial(初始): 10 mΩ max After(测试后): 15 mΩ max

3.4 VSWR(电压驻波比)

≦3GHz	3-6GHz
1.3 max	1.4 max

3.4.1 Test Method(测试方法):



4、Meannical Performance(机械性能)

4.1 Durability(寿命)	30 Cycles
4.2 Shock(冲击)	Accerlaration: 735m/s ² , 11ms (Time), Waveform: Half-wave waveform, 6 Cycles In Each X-Y-Zaxis 加速度: 735m/s ² , 11ms (时间), 波型: 半正弦波, 3个轴向各6个循环
4.3 Vibration (振动)	Frequency: 10-100Hz, single amplitude of 1.5mm, acceleration of 59m/s ² .for 5cycles in the direction of each of the 3axis. 频率: 10-100Hz, 单向幅度 1.5mm, 加速度: 59m/s ² , 3 个轴向各 5 个循环

 深圳市鸿源精密器材有限公司	Product Specification	DOC. No.:EB1-AS1C-223		Rev.: B	Page: 2/4
	PART No.:	Approved/Date		Checked/Date	Made/Date
	RF3-1717-085CE-CT	ZO 2016.03.04		W.P.Lu 2016.03.04	Y.Y.Chen 2016.03.04

5、Enviroment Performance (环境性能)

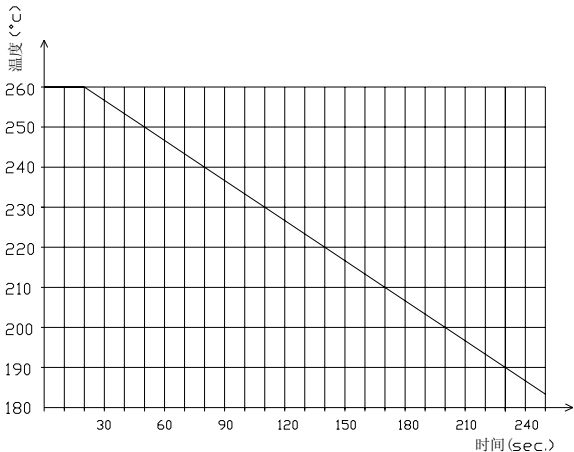
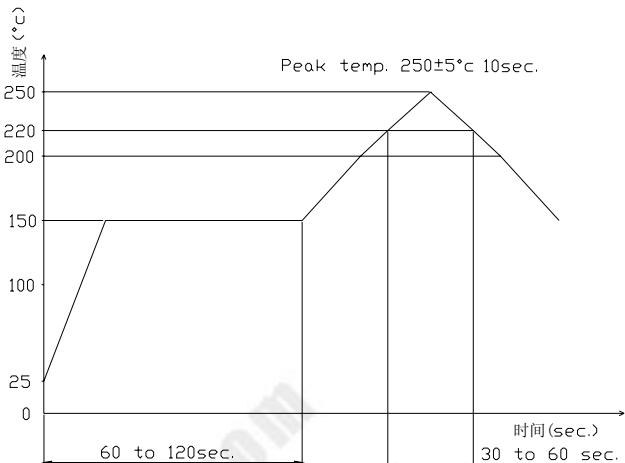
5.1 Temperature & Humidity Cycling (稳态湿热) TEM.: 60℃ Relative Humidity: 95% RH Time: 96 hours
温度: 40℃ 湿度: 95% RH 时间: 96 hours

5.2 Salt spray (盐雾试验) Temp.: 35℃ Conduction: 5% Time: 48 hours
温度: 35℃ 浓度: 5% 时间: 48 hours

5.3 Solderability (可焊性) The Sn Immersed Area must beyond by 95%.
吃锡面积 95%以上

6、SMT Temperature Curve （SMT 温度曲线图）

6.1 Recommanded tem.&time relative curve of Re-flow. 6.2 Extremed tem.&time curve of Re-flow
建议回流焊温度与时间条件 回流焊极限温度与时间条件



9、Packaging SPEC.（包装规格）

